

KMT 031 OL LHS

Ref. / PS-KMT-296

Page 1 of 6

rev. C

Approvals:

Laurent Kubat Engineering Manager

Date

Revision record:

Revision	Date	Comments
-	December 16 th 2010	Creation
rev. A	February 8 th , 2011	Update : (According to ECR N°6361)
		• IP code
rev. B	January 5 th , 2012	Update : (According to ECR N°7252)
		• KMT switch integration recommendation (§10)
rev. C	April 6 th , 2012	Update : (According to ECR N°7840)
		Packaging: 5000 p/reel instead of 4000 p/reel

Summary:

- 1. Description / Main Features
- 2. Construction
- 3. Electrical data
- 4. Mechanical data
- 5. Physical data
- 6. Operating environment
- 7. Additional data : storage and handling environment
- 8. Additional data : process environment
- 9. Applicable norms
- 10. KMT Switch integration recommendation

Appendix:

- > 1: Reflow profile characteristics
- > 2: Packaging

Note: This specification, attached documents and attached drawings cannot be communicated to anybody without written agreement of C&K.

April 2012



KMT 031 OL LHS

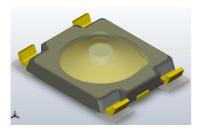
Ref. / PS-KMT-296

rev. C

April 2012

Page 2 of 6

1 - Description



The KMT 031 OL LHS is an ultra-low profile tact switch, single pole, normally open, momentary action, and designed for SMT mounting.

Main Features

- 0.65 mm height with actuator
- Version without ground
- Good tactile feed-back
- Terminal plating : LFS (Lead Free Silver)
- ROHS compliance
- Halogen Free compliance
 - Bromine (Br) \leq 900 ppm
 - Chlorine (Cl) ≤ 900 ppm
 - Total concentration of Br & Cl ≤ 1500 ppm
- Compatible with lead free reflow soldering process
- Delivered on plastic reels
- Compatible with Pick&Place machines

2 - <u>Construction</u>				
Function	Momentary action			
Contact type	Normally Open			
Terminals	4 SMT (J type)			
3 - <u>Electrical data</u>				
	Contact plating : silver			
Maximum power	0.5 VA			
Min/max voltage	20 mV – 32 Vdc			
Min/max current	1 mA – 50 mA			
Dielectric strength	≥ 250 Vrms (1 mn)			
Contact resistance	$\leq 150 \text{ m}\Omega$			
Insulation resistance	\geq 50 M Ω			
Bounce time	$\leq 6 \text{ ms}$			
4 - Mechanical data (after 2 reflow cycles)				
Operating force (Fa)	$Fa=3.4~N\pm25\%$			
Tactile feeling (Δ %)	$\Delta \ge 30\%$			
Return force (Frr)	$Frr \ge 0.5 N$			
Electrical travel (Te)	$Te=0.15\ mm\pm0.1$			
Mechanical travel (Tm)	$Tm=0.15\ mm\pm0.1$			
Simultaneity	≤ 0.05mm			
5 – <u>Physical data</u>				
Dimensions & layout	According to drawing : CU 34 MH2 006 FP			
Mass	$0.02~g\pm0.01$			
6 - <u>Operating environment</u>				
Operating temperatures	- 40 °C / + 85 °C			
Relative humidity	90 to 96 % According to NF EN 60068-2-78			
Operating life	\geq 300 000 cycles Contact resistance measurements after life test : \leq 5 Ω			
Vibrations	10-500 Hz / 10 g / 3 axis No discontinuity > 1μs According to NF EN 60068-2-6			
Mechanical shocks	¹ / ₂ sinusoidal / 50 g / 11 ms 3 shocks in each direction of the 3 axis No discontinuity > 1μs According to NF EN 60068-2-27			
Overload	Static Overload : 65 N – one actuation for 5s with diameter 3mm probe. Overload life test : 10 N – 1000 cycles			



April 2012

rev. C

KMT 031 OL LHS

Ref. / PS-KMT-296

Page 3 of 6

7 - Additional data : storage and handling environment				
	According to drawings in appendix 2			
	Tape and reel per EIA 481-BNumber of pieces per reel: 5000			
Packaging conditions	Dry pack with desiccant. Once dry pack is opened and a part of the reel unused for more one week, baking, prior to SMT 4 hour/60°C is recommended.			
Transport conditions	According to specification NF H00-060			
Storage temperatures	- 55 °C (10 days) / +85 °C (4 days)			
8 - Additional data : process environment				
Lead free reflow soldering process	According to C&K Procedure : PS-LF-001 (reflow profile characteristics described in appendix 1) Recommendation for solder paste thickness : $100 \ \mu m \pm 20 \ \mu m$			
Re-work process by iron soldering	N.A.			
Washing process	NA			
PCB coating	NA			
Sealing	IP 68			
Chemical agent	NA			
Shear test (switch/PCB)	> 30 N			
9 – <u>Applicable norms</u>				
Testing procedure (C&K spec)	Proc-essai 16			
Legal norm (EHS)	C&K procedure			
10 – <u>KMT Switch integration recommendation</u>				
PCB pad and stencil definition – P&P setup	According to C&K procedure: RU-KMT-006			



April 2012

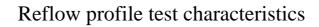
KMT 031 OL LHS

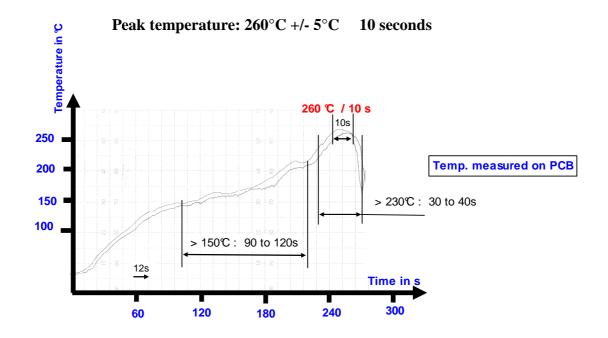
rev. C

Ref. / PS-KMT-296

Page 4 of 6

Appendix 1







April 2012

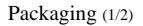
rev. C

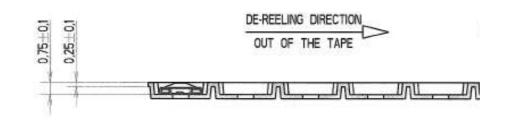
KMT 031 OL LHS

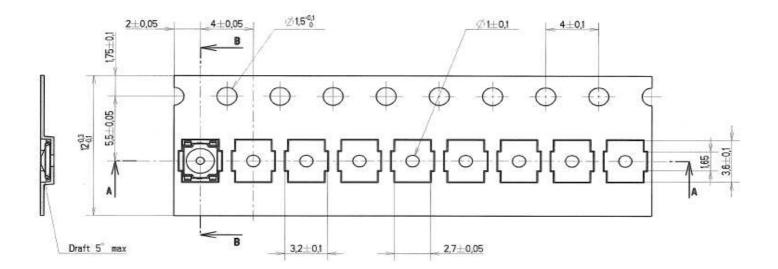
Ref. / PS-KMT-296

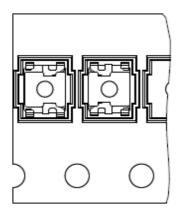
Page 5 of 6

Appendix 2









Be careful! Bottom view

Product are symetrical but can be presented in any 180° direction as shown on the left



April 2012

KMT 031 OL LHS

rev. C

Ref. / PS-KMT-296

Page 6 of 6

Appendix 2

Packaging (2/2)

